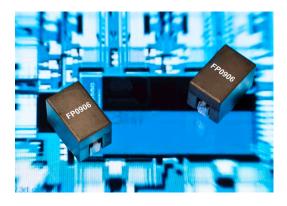
# FP0906

## High frequency, high current power inductors



### **Product Description**

- · High current carrying capacity
- · Low core loss
- · Controlled DCR for sensing circuits
- Frequency range up to 2MHz
- Inductance Range from 100nH to 300nH
- Current range from 32.5 to 94 amps
- 9.6x6.45mm footprint surface mount package in a 8.0mm height
- · Ferrite core material
- · Halogen free, lead free, RoHS compliant

#### **Applications**

- Multi-phase and Vcore regulators
- Voltage Regulator Modules (VRMs)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- · Graphics cards and battery power systems
- · Point-of-Load modules
- · DCR Sensing circuits

#### **Environmental Data**

- Storage temperature range (Component): -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant









## **Product specifications**

Part Number <sup>7</sup>	OCL <sup>1</sup> (nH) ±10%	FLL <sup>2</sup> (nH) minimum	l <sub>rms</sub> ³ (amps)	l <sub>sat</sub> 1 <sup>4</sup> (amps)	I <sub>sat</sub> 2 <sup>5</sup> (amps)	DCR (mΩ) ±5% @ 20°C	K-factor <sup>6</sup>
FP0906R1-R10-R	100	72	51	94	81	0.29	451
FP0906R1-R12-R	120	86	51	79	68	0.29	451
FP0906R1-R15-R	150	108	51	65	55	0.29	451
FP0906R1-R18-R	180	129	51	55	45	0.29	451
FP0906R1-R22-R	220	155	51	44	37.5	0.29	451
FP0906R1-R28-R	280	200	51	34	29	0.29	451
FP0906R1-R30-R	300	216	51	32.5	27.5	0.29	451

- 1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 1.0Vrms, 0.0Adc, +25°C
- 2. Full Load Inductance (FLL) Test Parameters: 100kHz, 1.0Vrms, I<sub>cot</sub>1, +25°C
- 3. I\_ms: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 4. I<sub>sat</sub>1 : Peak current for approximately 20% rolloff @ +25°C

- 5. I<sub>sat</sub>2: Peak current for approximately 20% rolloff @ +125°C
- 6. K-factor: Used to determine B<sub>no</sub> for core loss (see graph). B<sub>no</sub> = K \* L \* I \* 10<sup>-3</sup>. B<sub>no</sub> :(Gauss), K: (Kfactor from table), L: (Inductance in nH), I (Peak to peak ripple current in Amps).
- 7. Part Number Definition: FP0906Rx-Rxx-R

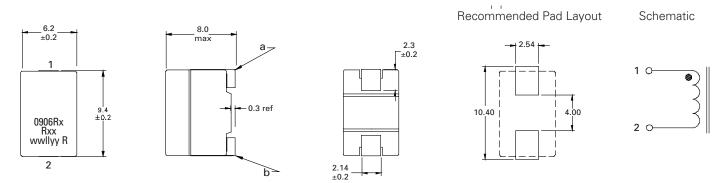
FP0906 = Product code and size

Rx= DCR indicator

Rxx= Inductance value in uH, R= decimal point

-R suffix = RoHS compliant

#### **Dimensions-mm**



Part marking: 0906Rx (Rx=DCR indicator), Rxx=Inductance value in uH (R=decimal point),

www=date code R=revision level

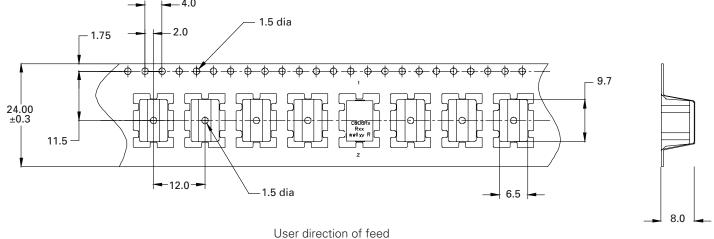
The nominal DCR is measured between point "a" and point "b"

Soldering surfaces to be coplanar within 0.1 millimeters

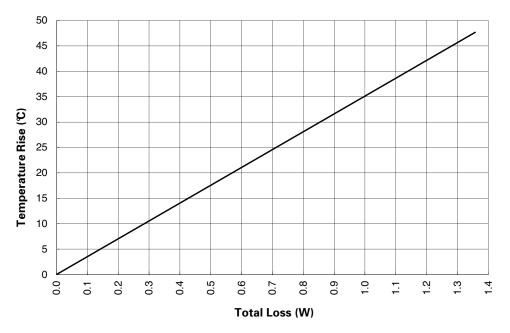
Do not route traces or vias underneath the inductor

#### Packaging-mm

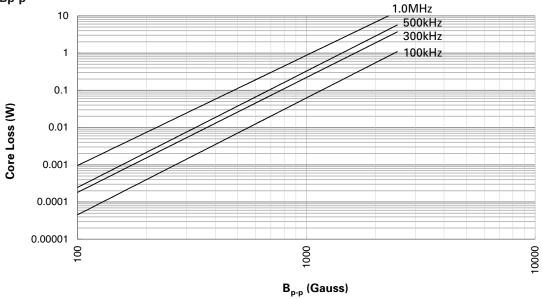
Supplied in tape and reel packaging, 600 parts per 13" diameter reel



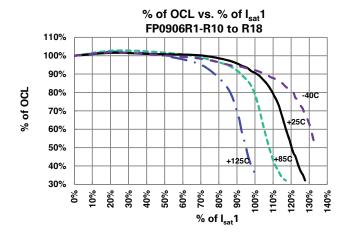
## Temperature rise vs. total loss

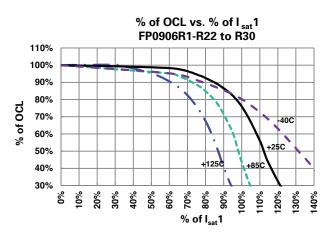


## Core loss vs Bp-p

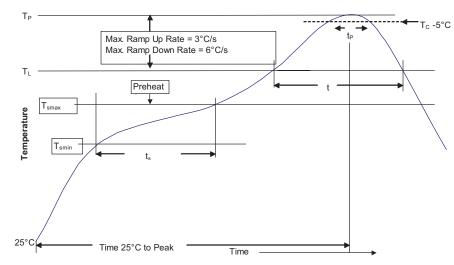


## Inductance characteristics





## Solder reflow profile



-<sub>Tc-5°C</sub> Table 1 - Standard SnPb Solder (T<sub>C</sub>)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T<sub>C</sub>)

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak • Temperature min. (T <sub>smin</sub> )	100°C	150°C
• Temperature max. (T <sub>smax</sub> )	150°C	200°C
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_{p}$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(T_c)$	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

<sup>\*</sup> Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Life Support Policy: Eaton does not authorize the use of any of its products for use in life support devices or systems without the express written approval of an officer of the Company. Life support systems are devices which support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

Eaton reserves the right, without notice, to change design or construction of any products and to discontinue or limit distribution of any products. Eaton also reserves the right to change or update, without notice, any technical information contained in this bulletin.

#### Eaton Electronics Division 1000 Eaton Boulevard Cleveland, OH 44122 United States

www.eaton.com/elx

© 2015 Eaton All Rights Reserved Printed in USA Publication No. 4407 BU-SB14111 June 2015



<sup>\*\*</sup> Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.